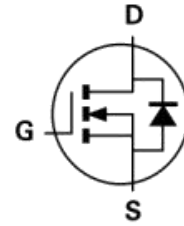


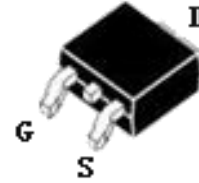
### MAIN CHARACTERISTICS

$I_D$	100A
$V_{DSS}$	100V
$R_{DS(on)-typ}$ (@ $V_{GS}=10V$ )	5.3m $\Omega$



### FEATURES

- Best-in-Class FOM
- Low Gate Charge
- High Current Capability



TO-252

### APPLICATIONS

- Power Management in Telecom., Industrial Automati
- Motor Driving in Power Tool, E-vehicle, Robotics
- Current Switching in DC/DC&AC/DC(SR) Sub-system

### MECHANICAL DATA

- Case: Molded plastic
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275°C maximum, 10s per JESD 22-B106

### Product specification classification

Part Number	Package	Mode Name	Pack
LG100N10AD	TO-252	LG100N10AD	Tape

### Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continue Drain Current	$I_D$	100	A
Pulsed Drain Current (Note1)	$I_{DM}$	360	A
Power Dissipation	$P_D$	96	W
Single Pulse Avalanche Energy (Note1)	$E_{AS}$	216	mJ
Operating Temperature Range	$T_J$	150	°C
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.7	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	50	°C/W

Note1:Pulse test: 300 μs pulse width, 2 % duty cycle

### Electrical Characteristics at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_D = 250 \mu A$	$BV_{DSS}$	100	-	-	V
Drain-Source Leakage Current	$V_{DS} = 100 V, V_{GS} = 0 V$	$I_{DSS}$	-	-	1	μA
Gate Leakage Current	$V_{GS} = \pm 20 V, V_{DS} = 0 V$	$I_{GSS}$	-	-	±100	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	$V_{GS(th)}$	1.2	-	2.5	V
Drain-Source On-State Resistance	$V_{GS} = 10 V, I_D = 20 A$	$R_{DS(on)}$	-	5.3	6.4	mΩ
	$V_{GS} = 4.5 V, I_D = 15 A$	$R_{DS(on)}$	-	7.5	9.4	mΩ
Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	$C_{iss}$	-	2420	-	pF
Output Capacitance		$C_{oss}$	-	900	-	pF
Reverse Transfer Capacitance		$C_{rss}$	-	35	-	pF
Turn-on Delay Time(Note2)		$t_{d(ON)}$	-	11.2	-	ns
Rise Time(Note2)	$V_{DD}=50V, V_{GS}=10V, RG=3\Omega, I_D=20 A$	$t_r$	-	23	-	ns
Turn-Off Delay Time(Note2)		$t_{d(OFF)}$	-	38	-	ns
Fall Time(Note2)		$t_f$	-	15.3	-	ns
Total Gate Charge(Note2)		$Q_G$	-	43	-	nC
Gate to Source Charge(Note2)	$V_{DS}=50V, V_{GS}=10V, I_D=20A$	$Q_{GS}$	-	9.4	-	nC
Gate to Drain Charge(Note2)		$Q_{GD}$	-	10.3	-	nC

### Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current		$I_S$	-	-	100	A
Drain-Source Diode Forward Voltage	$V_{GS}=0V, I_S=20A, T_J=25^\circ C$	$V_{SD}$	-	-	1.2	V
Reverse Recovery Time(Note2)	$T_J = 25^\circ C, I_F = 20A$ $di / dt = 100 A/\mu s$	$t_{rr}$	-	42	-	ns
Reverse Recovery Charge(Note2)		$Q_{rr}$	-	46	-	nC

Note2:Pulse test: 300 μs pulse width, 2 % duty cycle

### RATINGS AND CHARACTERISTIC CURVES

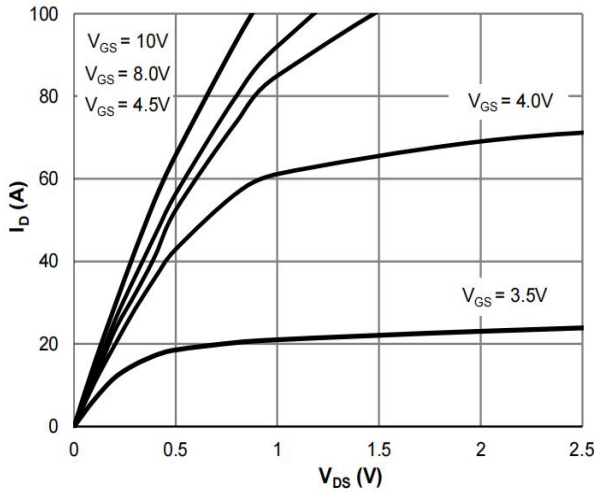


Figure 1: Saturation Characteristics

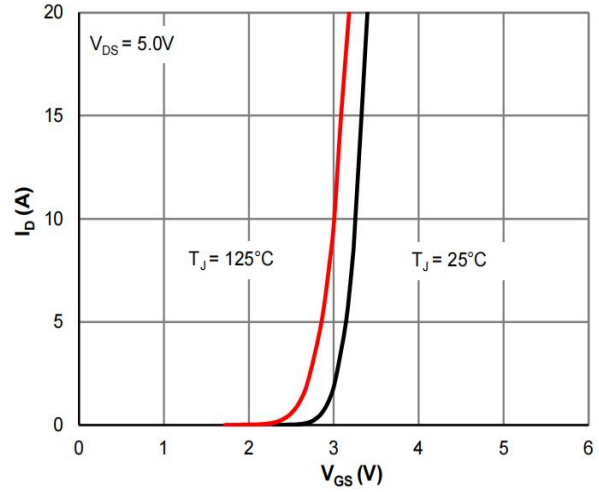


Figure 2: Transfer Characteristics

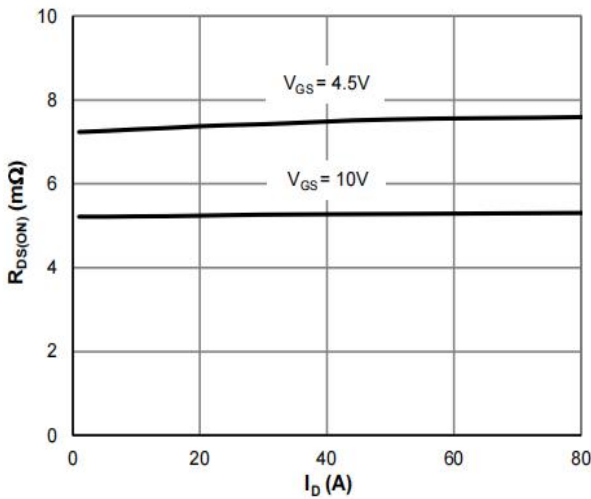


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

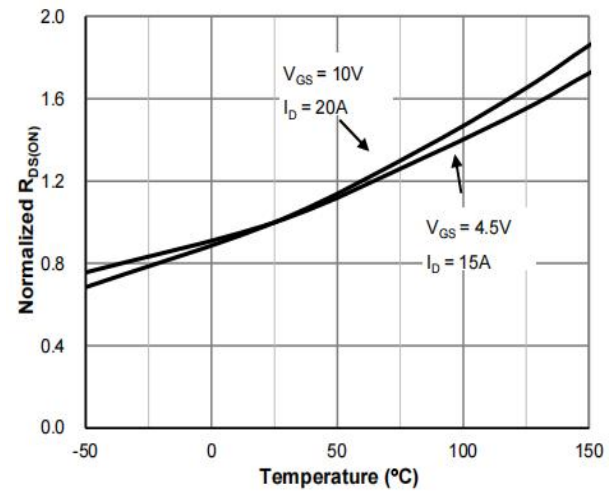


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

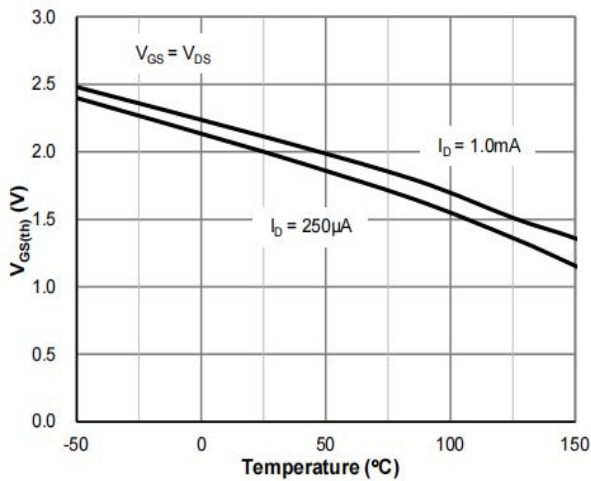


Figure 5:  $V_{GS(th)}$  vs. Junction Temperature

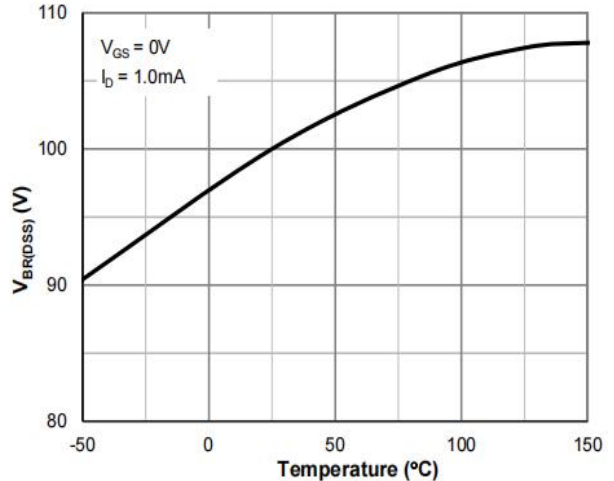


Figure 6:  $V_{BR(DSS)}$  vs. Junction Temperature

### RATINGS AND CHARACTERISTIC CURVES

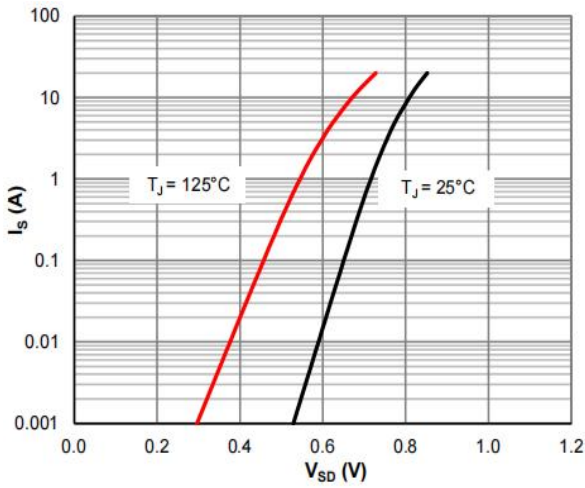


Figure 7: Body-Diode Characteristics

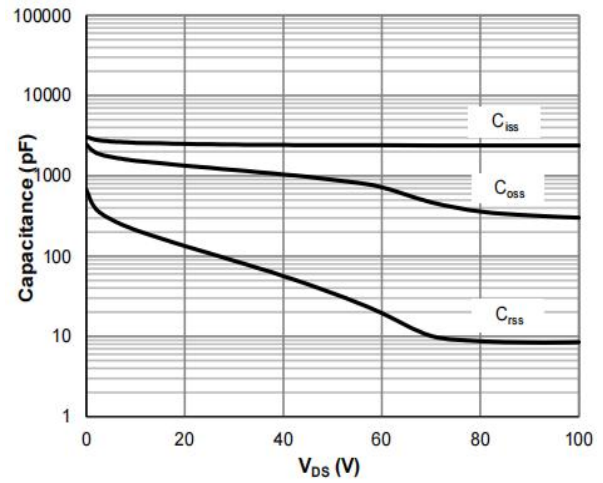


Figure 8: Capacitance Characteristics

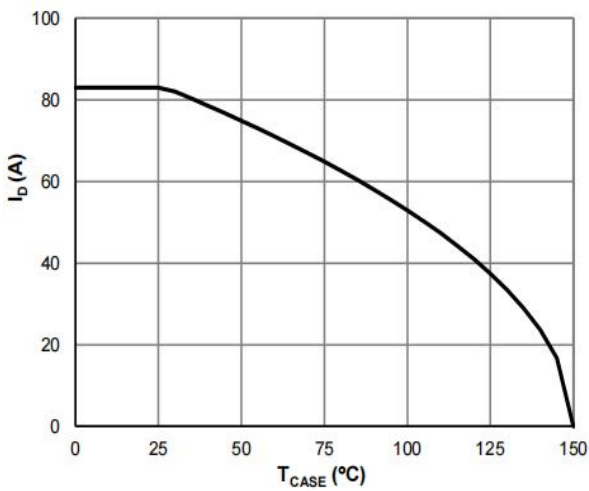


Figure 9: Current De-rating

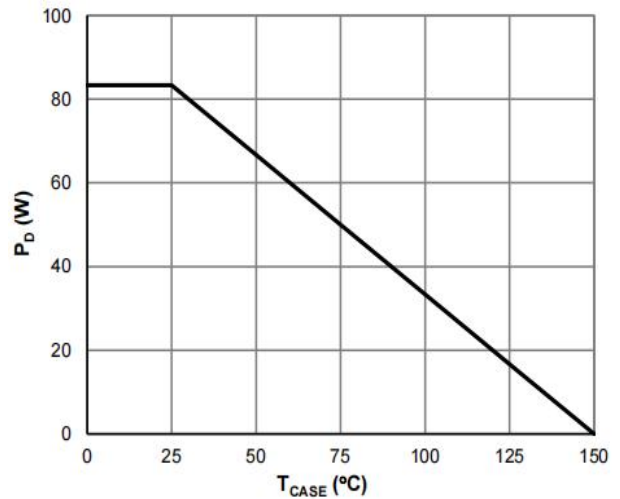


Figure 10: Power De-rating

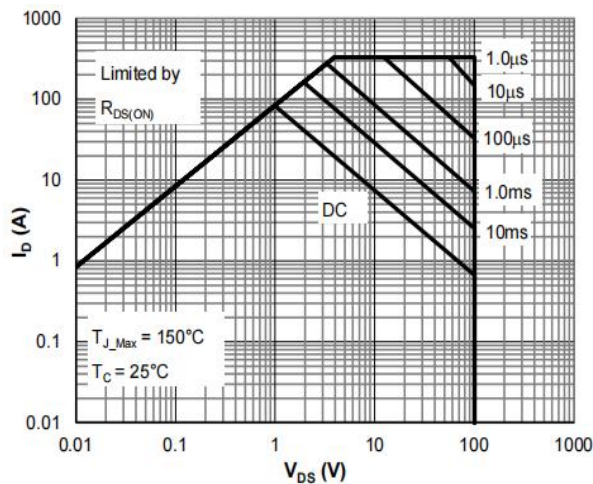


Figure 11: Maximum Safe Operating Area

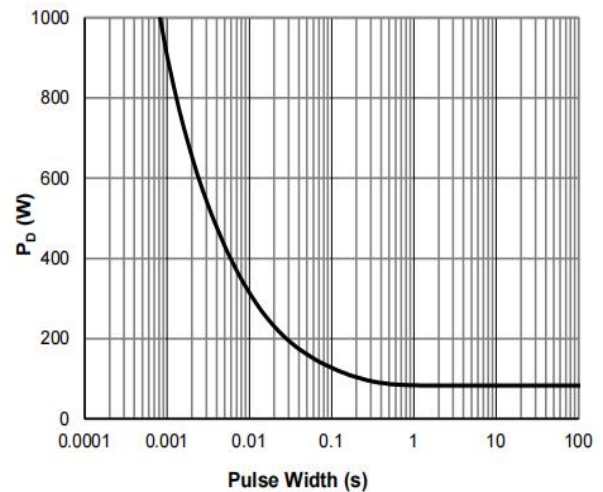
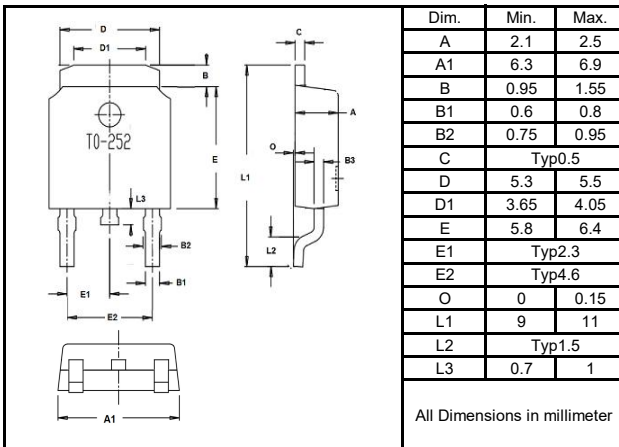


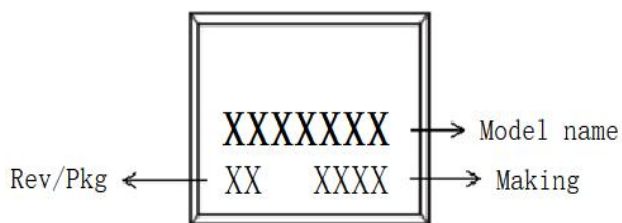
Figure 12: Single Pulse Power Rating, Junction-to-Case

### Package Outline Dimensions millimeters

TO-252



### Marking on the body



MAKING:

X X XX

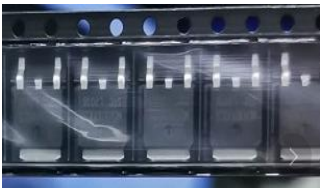


Assembly code ( e.g : AB,CD,..... )

month - code (WW: 1-1, 10-A...)

Year - code

(Y: Last digit of year & A:2012,B:2013...)

### packing instruction

PKG	最小包装	内盒	外箱
TO-252			
	2500pcs/盘	5000pcs/盒	25000pcs/箱

### Notice

All product, product specifications and data are subject to change without notice to improve. The right to explain is owned by LINGXUN electronics

company.

Confirm that operation temperature is within the specified range described in the product specification. Avoid applying power exceeding normal rated

power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

LINGXUN electronics shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.